

PMP4412 BOM

2/12/2014

| Item | Qty | Reference | Description | Size | Value | MFR |
|------|-----|-----------|--|---------|----------------|----------|
| 1 | 1 | C20 | Capacitor, Ceramic, | 0603 | 0.01uF/25V | STD |
| 2 | 1 | C44 | Capacitor, Ceramic, | 0603 | 1nF/50V | STD |
| 3 | 1 | C22 | Capacitor, Ceramic, | 0603 | 1uF/16V | STD |
| 4 | 1 | C1 | Capacitor, Ceramic, | 0603 | 3.3nF/50V | STD |
| 5 | 1 | C50 | Capacitor, Ceramic, | 0603 | NA | STD |
| 6 | 2 | C4-5 | CAP CER 10UF 10V X7R 0805 | 0805 | 10uF | STD |
| 7 | 2 | C2-3 | Capacitor, Ceramic, | 0805 | NA | STD |
| 8 | 1 | C7 | CAP CER 1UF 35V X7R 0805 | 0805 | 1uF/35V | STD |
| 9 | 1 | C6 | CAP CER 2.2UF 16V X7R 0805 | 0805 | 2.2uF/16V | STD |
| 10 | 1 | J1 | Connector, 100 mil Pitch | | | STD |
| 11 | 1 | D3 | Diode | SOD-323 | NA | STD |
| 12 | 1 | U12 | 48V, 325mA Wide Vin Synchronous Step-down Regulator with Integrated MOSFETs | WSON-8 | LM25018SD/NOPB | TI |
| 13 | 1 | T1 | MTC-0016SG | | | MNC |
| 14 | 2 | R1-2 | Resistor, Chip, 1/10W, 1% | 0603 | NA | STD |
| 15 | 1 | R3 | Resistor, Chip, 1/10W, 1% | 0603 | 10K | STD |
| 16 | 1 | R34 | Resistor, Chip, 1/10W, 1% | 0603 | 11K | STD |
| 17 | 1 | R69 | Resistor, Chip, 1/10W, 1% | 0603 | 20K | STD |
| 18 | 1 | R32 | Resistor, Chip, 1/10W, 1% | 0603 | 240K | STD |
| 19 | 1 | R5 | Resistor, Chip, 1/10W, 1% | 0603 | 4.3K | STD |
| 20 | 1 | R33 | Resistor, Chip, 1/10W, 1% | 0603 | 62K | STD |
| 21 | 1 | R4 | Resistor, Chip, 1/10W, 1% | 0603 | NA | STD |
| 22 | 1 | D2 | DIODE SCHOTTKY 40V 0.4A SOD323 | SOD-323 | ZHCS400 | Infineon |
| 23 | 1 | D1 | DIODE | SOD-323 | NA | STD |
| 24 | 1 | D5 | Diode, Zener, 5.6V, 400mW, SOD-323 | SOD-323 | 5.6V | STD |
| 25 | 1 | D4 | Diode, Zener | SOD-323 | NA | STD |

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